

## QIAOXIN N-Channel **Super Trench II** Power MOSFET

### Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(on)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

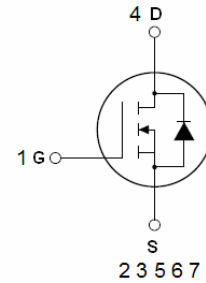
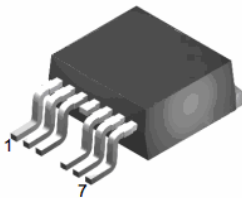
### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

### General Features

- $V_{DS} = 120V, I_D = 190A$   
 $R_{DS(on)} = 2.5m\Omega$ , typical @  $V_{GS} = 10V$
- Excellent gate charge x  $R_{DS(on)}$  product(FOM)
- Very low on-resistance  $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating

**TO-263-6L**



**Schematic Diagram**

### Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VCRRP035N12VD	VCRRP035N12VD	TO-263-6L	-	-	-

### Absolute Maximum Ratings ( $T_C = 25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	120	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	190	A
Drain Current-Continuous( $T_C = 100^\circ C$ )	$I_D(100^\circ C)$	135	A
Pulsed Drain Current	$I_{DM}$	760	A
Maximum Power Dissipation	$P_D$	300	W
Derating factor		2	W/°C
Single pulse avalanche energy <sup>(Note 5)</sup>	$E_{AS}$	2300	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Case <sup>(Note 2)</sup>	$R_{\theta JC}$	0.5	°C/W
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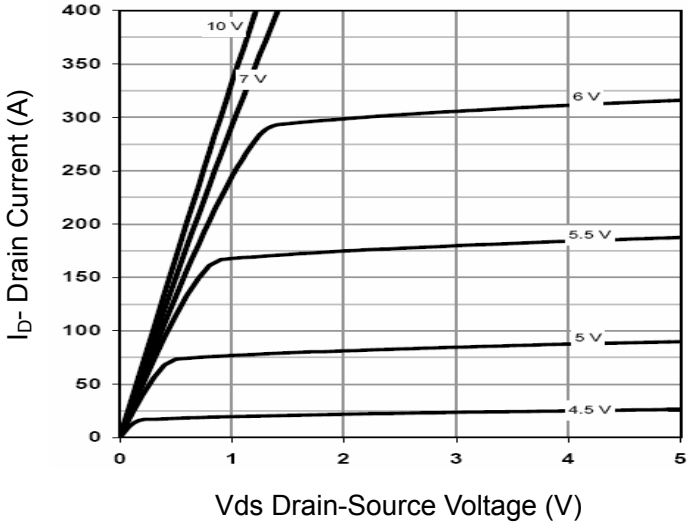
### Electrical Characteristics (T<sub>C</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	120		-	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =120V, V <sub>GS</sub> =0V	-	-	1	μA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±100	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250μA	2.0	3.0	4.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =95A	-	2.5	3.5	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =95A		90	-	S
<b>Dynamic Characteristics</b> (Note 4)						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, F=1.0MHz	-	12700	-	PF
Output Capacitance	C <sub>oss</sub>		-	870	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	48	-	PF
<b>Switching Characteristics</b> (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =60V, I <sub>D</sub> =95A V <sub>GS</sub> =10V, R <sub>G</sub> =1.6Ω	-	34	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	27	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>		-	78	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	30	-	nS
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =50V, I <sub>D</sub> =95A, V <sub>GS</sub> =10V	-	213	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	58		nC
Gate-Drain Charge	Q <sub>gd</sub>		-	58		nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =95A	-		1.2	V
Diode Forward Current (Note 2)	I <sub>S</sub>		-	-	190	A
Reverse Recovery Time	t <sub>rr</sub>	T <sub>J</sub> = 25°C, I <sub>F</sub> = 100A di/dt = 100A/μs (Note 3)	-	101	-	nS
Reverse Recovery Charge	Q <sub>rr</sub>		-	280	-	nC

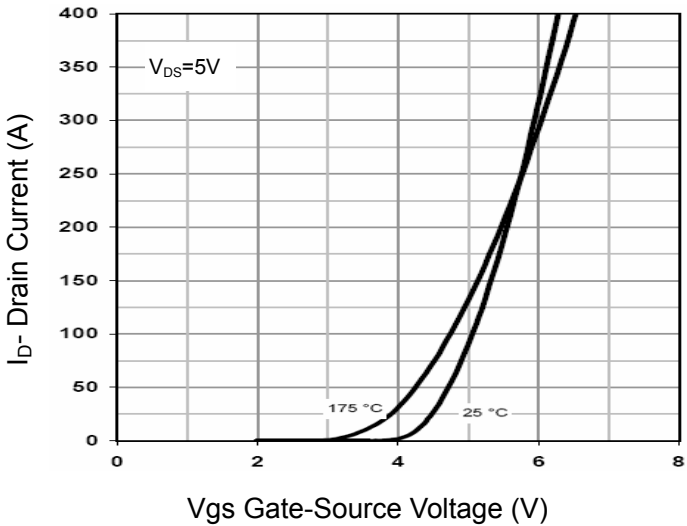
#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition : T<sub>J</sub>=25°C, V<sub>DD</sub>=60V, V<sub>G</sub>=10V, L=0.5mH, R<sub>G</sub>=25Ω

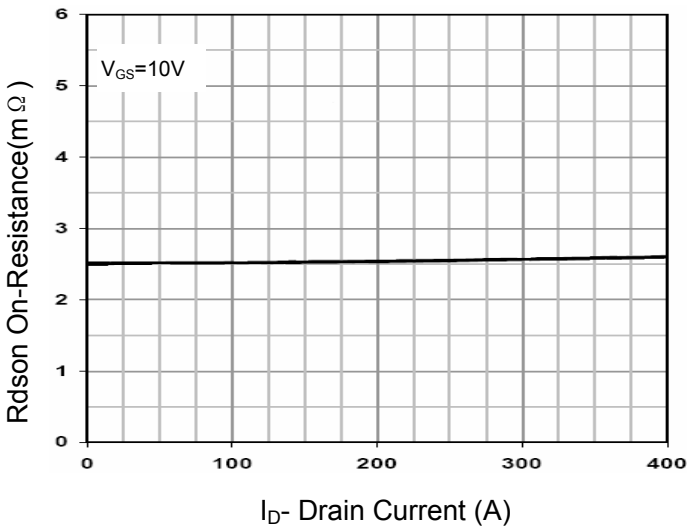
**Typical Electrical and Thermal Characteristics**



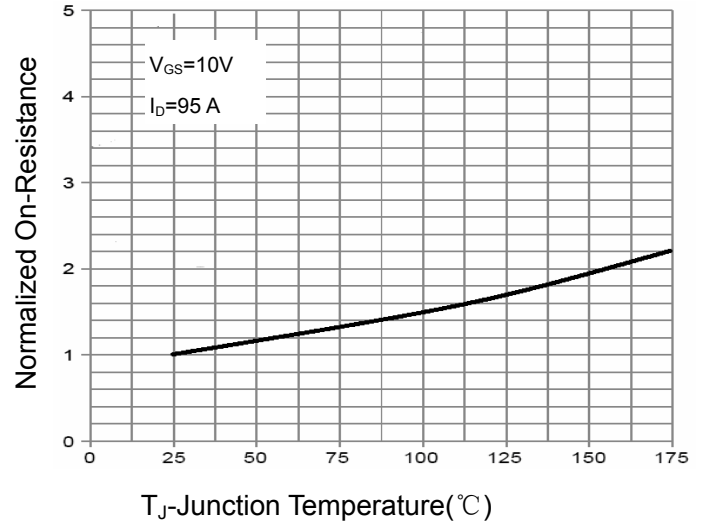
**Figure 1 Output Characteristics**



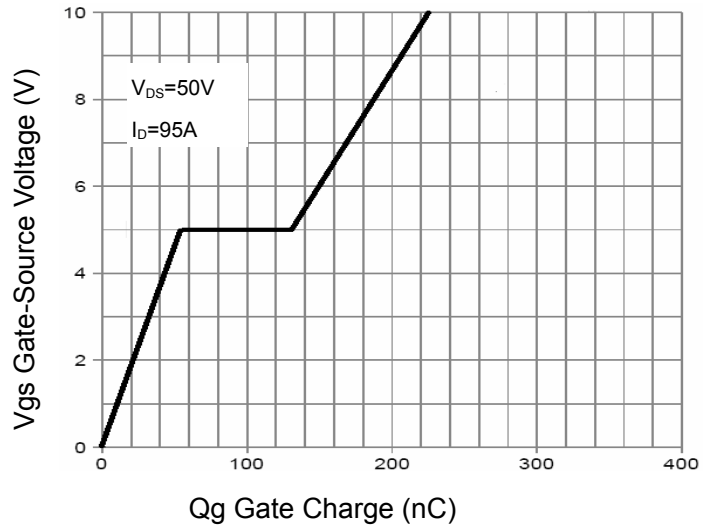
**Figure 2 Transfer Characteristics**



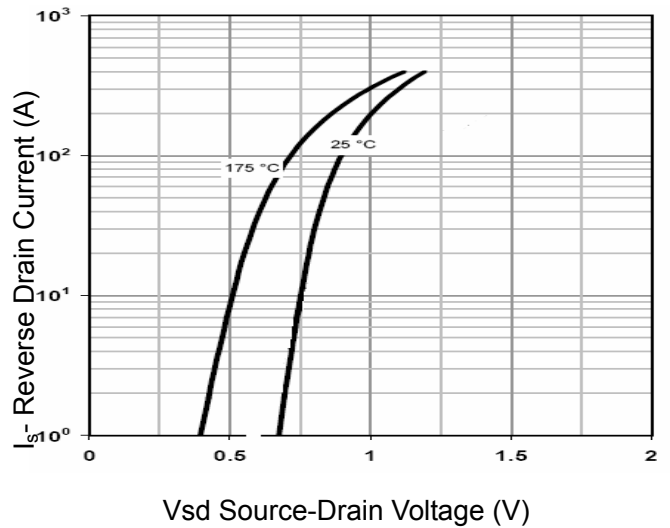
**Figure 3 Rdson- Drain Current**



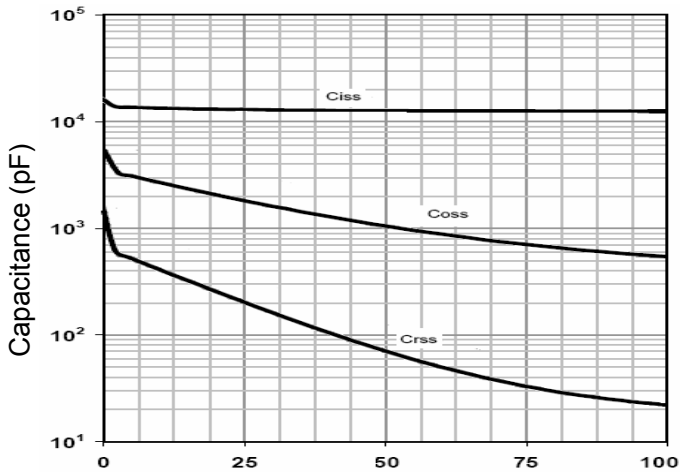
**Figure 4 Rdson-Junction Temperature**



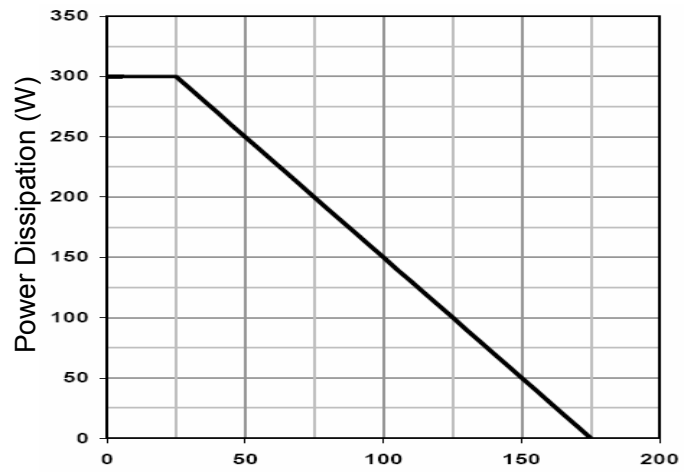
**Figure 5 Gate Charge**



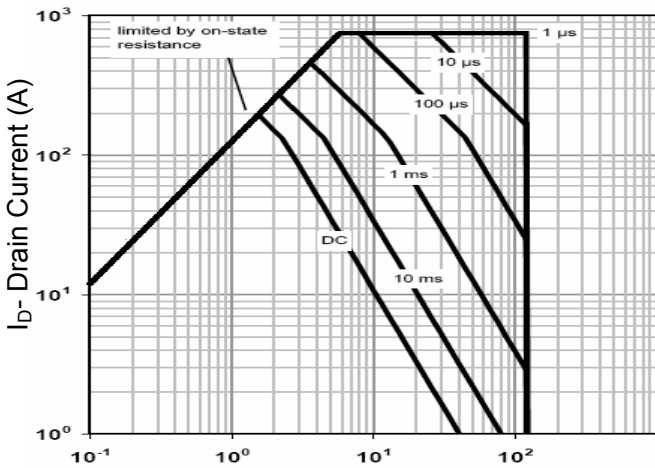
**Figure 6 Source- Drain Diode Forward**



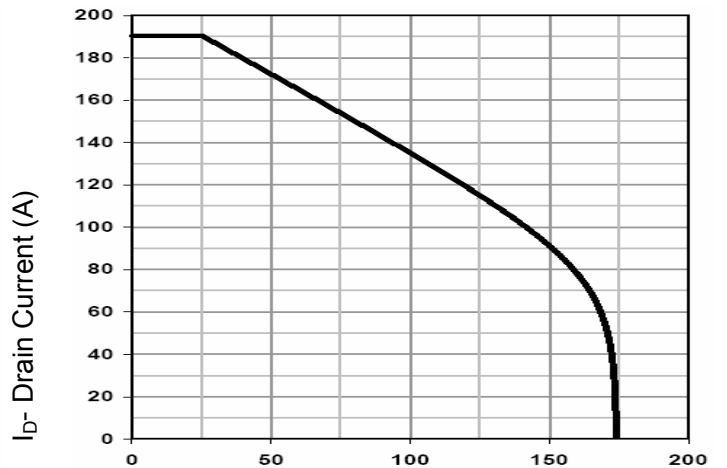
Vds Drain-Source Voltage (V)  
**Figure 7 Capacitance vs Vds**



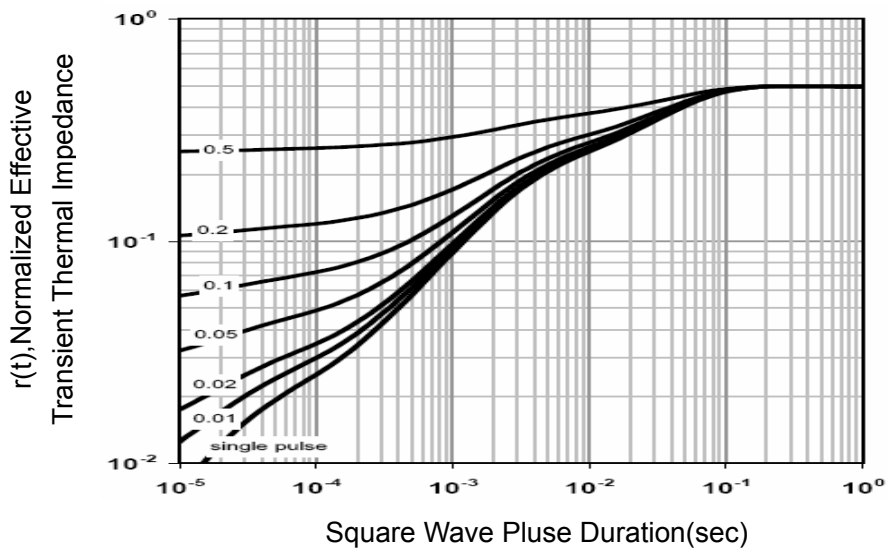
T<sub>J</sub>-Junction Temperature(°C)  
**Figure 9 Power De-rating**



Vds Drain-Source Voltage (V)  
**Figure 8 Safe Operation Area**

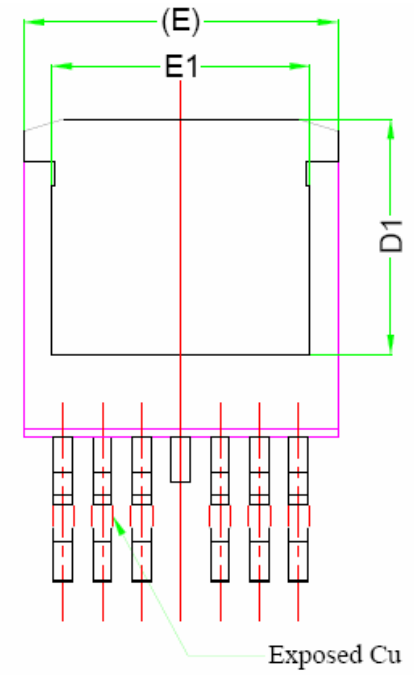
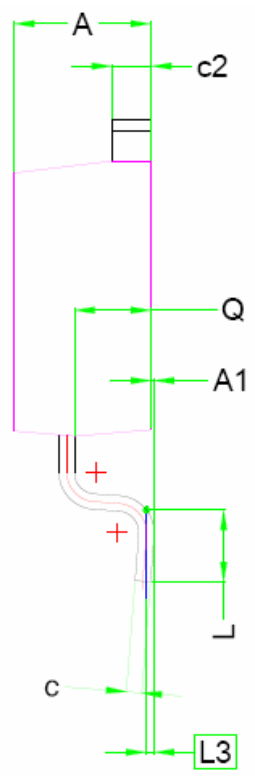
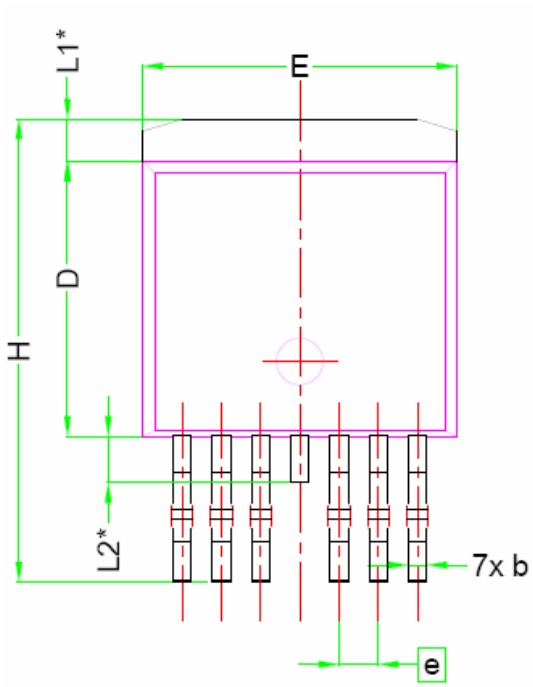


T<sub>J</sub>-Junction Temperature (°C)  
**Figure 10 Current De-rating**

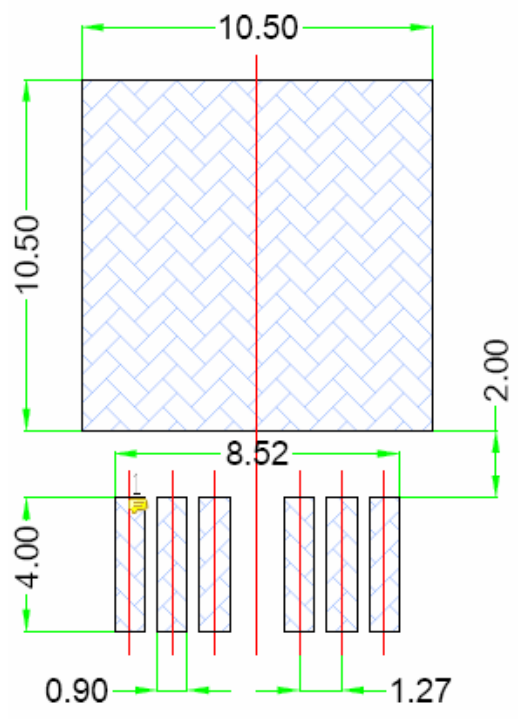


**Figure 11 Normalized Maximum Transient Thermal Impedance**

**TO-263-6L Package Information**



Land Pattern  
(Only for Reference)



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.24	4.44	4.64
A1	0.00	0.10	0.25
b	0.50	0.60	0.70
c	0.40	0.50	0.60
c2	1.15	1.27	1.40
D	8.82	8.92	9.02
D1	6.86	7.65	---
E	9.96	10.16	10.36
E1	8.20	8.35	8.50
e	1.27 BSC		
H	14.61	15.00	15.88
L	1.78	2.32	2.79
L1	1.36 REF.		
L2	1.50 REF.		
L3	0.25 BSC		
Q	2.30	2.48	2.70

### **Attention**

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